

S = 0.38 μ m GOLD/GXT
ON CONTACT AREA
2 μ m MIN MATTE
TIN ON TAIL

2µm MIN MATTE
TIN ON TAIL

G = 0.76μm GOLD/GXT
ON CONTACT AREA
2μm MIN MATTE
TIN ON TAIL

F = GOLD FASH
ON CONTACT AREA
2μm MIN MATTE

1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR BLACK
2. MATERIAL TERMINAL: COPPER ALLOY
3. TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
4. 7N MIN. PIN RETENTION IN EITHER DIRECTION.

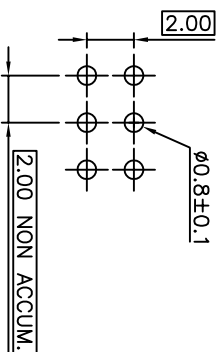
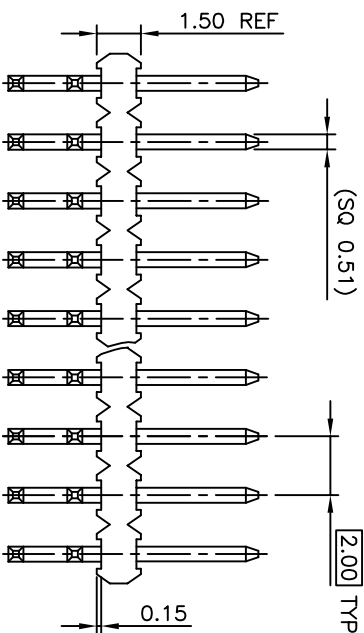
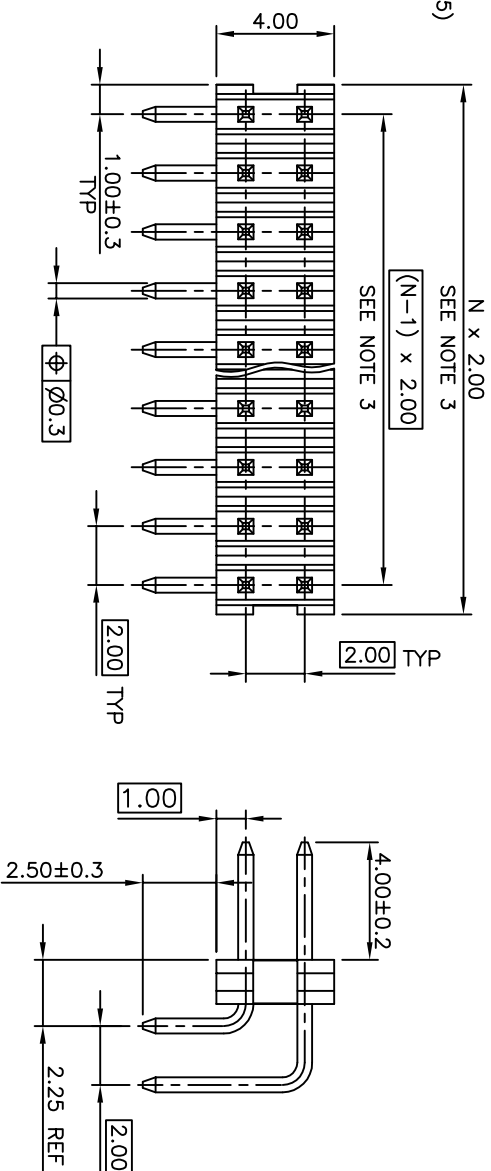
= PLASTIC BOX
U = TUBE AVAILABLE FROM 06 TO 50 POS

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C $\pm$ 5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

MEETS PACKAGING SPECS AS PER GS-14-920
- THIS PRODUCT MEETS EUROPEAN DIRECTIVES
AND OTHER COUNTRY REGULATIONS AS DISCIBED
IN GS-47-0004



mat'l. code		surface		tolerance		projection		product family	
		ISO 1302	✓	ISO 406	ISO 150			MINITEK	
ltr	ecm no	dr	date	tolerances unless otherwise specified				title	
A	F10338	LMU	03.10.01	X ±0.3				UNSHR HEADER	
B	P04-0351	JCO	05.01.13	linear X.X ±0.13				RIGHT ANGLE TMT	
C	T06-0210	LMU	06.07.05	X.XX ±0.05		scale 1:1			
D	T08-0145	ELA	17.04.08	dr				dwg no	
E	B-19190	LMU	14.10.24	eng'ng				sheet 1 of 1	
				COMPAGNON				size	
								A3	
sheet		revision						type	
index	sheet			JM.C		04.09.28		CUSTOMER Drawing	